


# PRODUCT / PROCESS CHANGE NOTIFICATION

## 1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	MICROCONTROLLERS/25/15305
1.3 Title of PCN	ST ROUSSET (France) additional source for STM32F411x , STM32F412x and STM32F76x/F77x listed products in M10/90nm technology.
1.4 Product Category	STM32F411x, STM32F412x, STM32F765x, STM32F767x, STM32F769x, STM32F777x and STM32F779x
1.5 Issue date	2025-05-07

## 2. PCN Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

## 3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Wafer fabrication (SOP 2617)	ST Rousset (France)

## 4. Description of change

	Old	New
4.1 Description	<p>Front-end sources for Die 431 cut1.0 :</p> <ul style="list-style-type: none"> <li>- ST Crolles (France) CR300 revision A</li> <li>- TSMC (Taiwan) FAB14 revision 1</li> </ul> <p>Front-end sources for Die 441 cut3.0 :</p> <ul style="list-style-type: none"> <li>- ST Crolles (France) CR300 revision C</li> <li>- TSMC (Taiwan) FAB14 revision 1</li> </ul> <p>Front-end sources for Die 451 cut1.1 :</p> <ul style="list-style-type: none"> <li>- ST Crolles (France) CR300 revision Z</li> <li>- TSMC (Taiwan) FAB14 revision 1</li> </ul>	<p>Front-end sources for Die 431 cut1.0 :</p> <ul style="list-style-type: none"> <li>- ST Crolles (France) CR300 revision A</li> <li>- TSMC (Taiwan) FAB14 revision 1</li> </ul> <p>Additional source</p> <ul style="list-style-type: none"> <li>- ST Rousset (France) RS8F revision 3</li> </ul> <p>Front-end sources for Die 441 cut3.0 :</p> <ul style="list-style-type: none"> <li>- ST Crolles (France) CR300 revision C</li> <li>- TSMC (Taiwan) FAB14 revision 1</li> </ul> <p>Additional source</p> <ul style="list-style-type: none"> <li>- ST Rousset (France) RS8F revision 2</li> </ul> <p>Front-end sources for Die 451 cut1.1 :</p> <ul style="list-style-type: none"> <li>- ST Crolles (France) CR300 revision Z</li> <li>- TSMC (Taiwan) FAB14 revision 1</li> </ul> <p>Additional source</p> <ul style="list-style-type: none"> <li>- ST Rousset (France) RS8F revision 2</li> </ul>
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No change on Form, Fit or Function - same datasheets	

## 5. Reason / motivation for change

5.1 Motivation	Due to the success on the market of STM32 devices, ST Microcontrollers Division decided to qualify an additional front-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	SERVICE IMPROVEMENT

## 6. Marking of parts / traceability of change

<b>6.1 Description</b>	Change is visible through diffusion traceability plant, in the marking: - "9R" for TSMC Fab14 (Taiwan) - "VQ" for ST Crolles (France) - "VG" for ST Rousset (France) Please refer to PCN 15305– Additional information attached document.
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7. Timing / schedule	
<b>7.1 Date of qualification results</b>	2025-07-30
<b>7.2 Intended start of delivery</b>	2025-11-04
<b>7.3 Qualification sample available?</b>	Upon Request

8. Qualification / Validation			
<b>8.1 Description</b>	15305 PCN15305_MDRF-GPAM-RER2417_M10 C300 to R8 - Die 431-441-451- Rel Plan.pdf		
<b>8.2 Qualification report and qualification results</b>	Available (see attachment)	<b>Issue Date</b>	2025-05-07

9. Attachments (additional documentations)
15305 Public product.pdf 15305 PCN15305_MDRF-GPAM-RER2417_M10 C300 to R8 - Die 431-441-451- Rel Plan.pdf 15305 _Additional information.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F411VCT6	
	STM32F411VEH6	
	STM32F411VET6	
	STM32F765ZGT6	
	STM32F767IIT6	
	STM32F767NIH6	
	STM32F767ZIT6	
	STM32F777IIT6	

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